

LTM4607 141LD 15mm X 15mm X 2.82mm (TABLE OF MATERIAL DECLARATION)

The LTM4607 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1453	Barium Compounds	7727-43-7	0.0021800	1.50
				Filler Substances (Silica Crystalline)	13776-74-4, 7631-86-9	0.0579960	39.91
				Copper Metal	7440-50-8	0.0813680	56.00
				Copper Compounds	1328-53-6	0.0000262	0.02
				Ecotoxic substances	7439-92-1	0.0000006	0.00
				Gold metal or alloy	7440-57-5	0.0006684	0.46
				Nickel	7440-02-0	0.0030513	2.10
2	Solder Paste	Alloy	0.0216	Zinc	7440-66-6	0.0000108	0.01
				Sn	7440-31-5	0.0204858	95.00
3	Passive/Active Components		0.1421	Sb	7440-36-0	0.0010782	5.00
				Copper (Cu)	7440-50-8	0.0454700	32.00
				Nickel (Ni)	7440-02-0	0.0113700	8.00
				Tin (Sn)	7440-31-5	0.0034100	2.40
4	Active Ics	Silicon	0.0183	Ceramic (Ba) Compounds	12047-27-7	0.0818500	57.60
5	Wire	Gold	0.0029	Silicon	7440-21-3	0.0182911	100.00
7	Encapsulation	Epoxy Resin	1.1612	Au	7440-57-5	0.0029360	99.99
				Fused Silica	60676-86-0	0.8964310	77.20
				Epoxy Resin	non-disclosure	0.1033450	8.90
				Phenol Resin	non-disclosure	0.1033450	8.90
				Crytalline Silica	14808-60-7	0.0348354	3.00
				Carbon Black	1333-86-4	0.0058059	0.50
				Metal Hydroxide	non-disclosure	0.0174177	1.50
Total Package Weight			1.4914				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts